

# A Q-Factor Enhancement Technique for MMIC Inductors

Mina Danesh, John R. Long  
University of Toronto, Canada

R. A. Hadaway<sup>1</sup> and D. L. Harame<sup>2</sup>

<sup>1</sup>Nortel Technology, Ottawa, Canada

<sup>2</sup>IBM Microelectronics, Burlington, VT

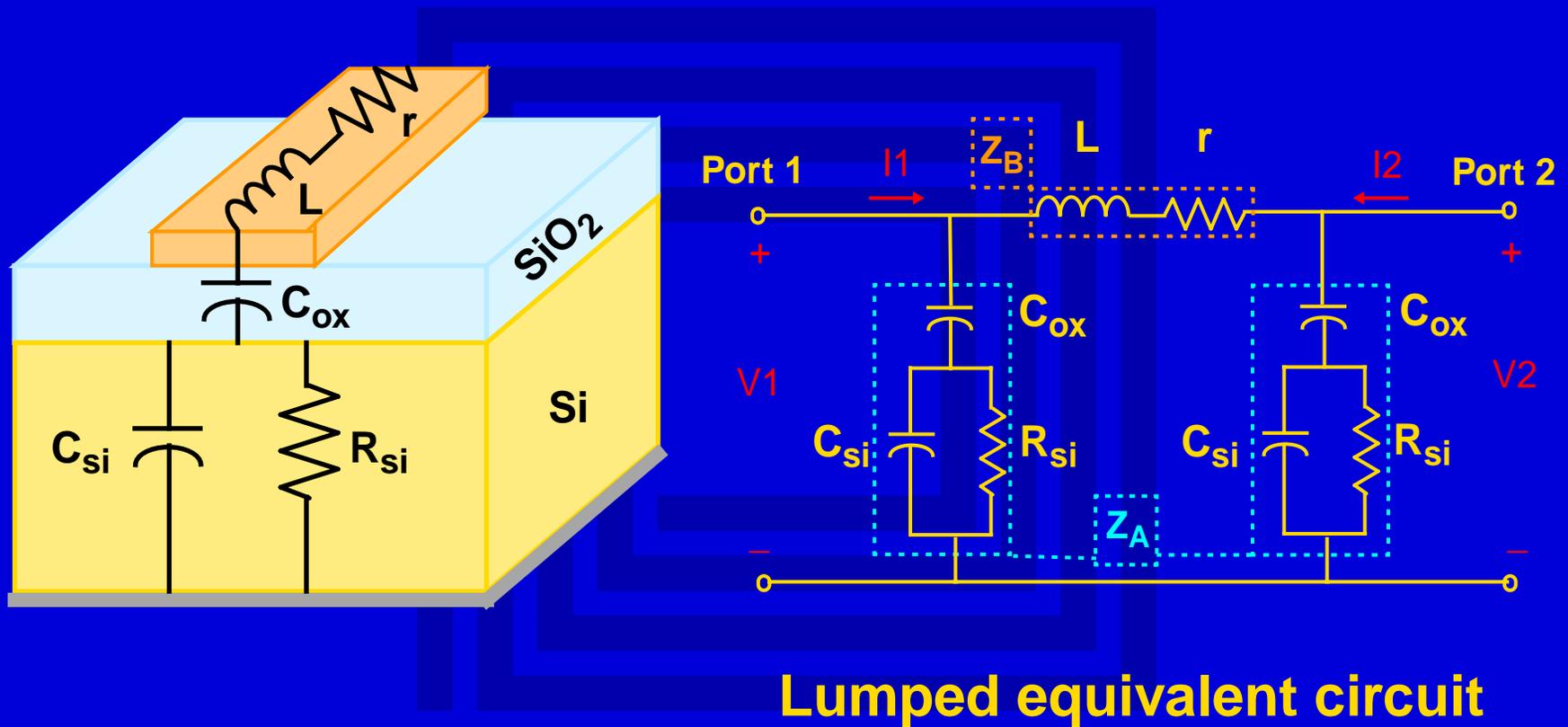


# Outline

- Introduction
- Differential excitation  
for higher Q-factor realization
- Symmetric spiral inductors
- Results
- Applications
- Conclusion



# Microstrip Line Modeling



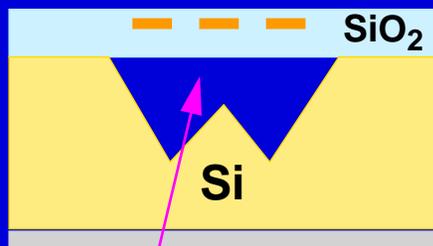
Lumped equivalent circuit



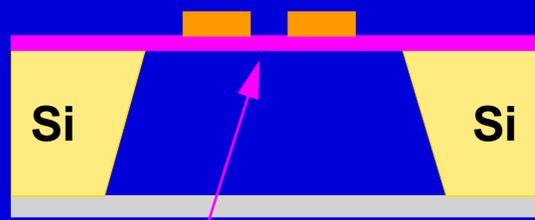
# Inductor Realizations in Si



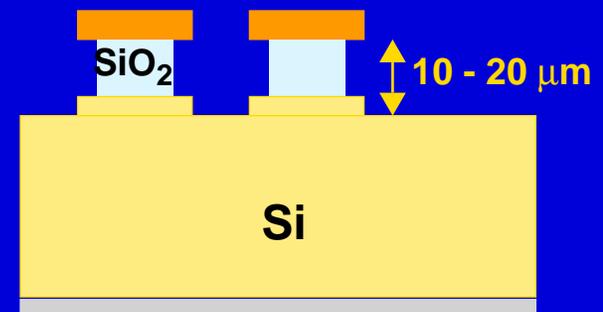
## Alternate structures



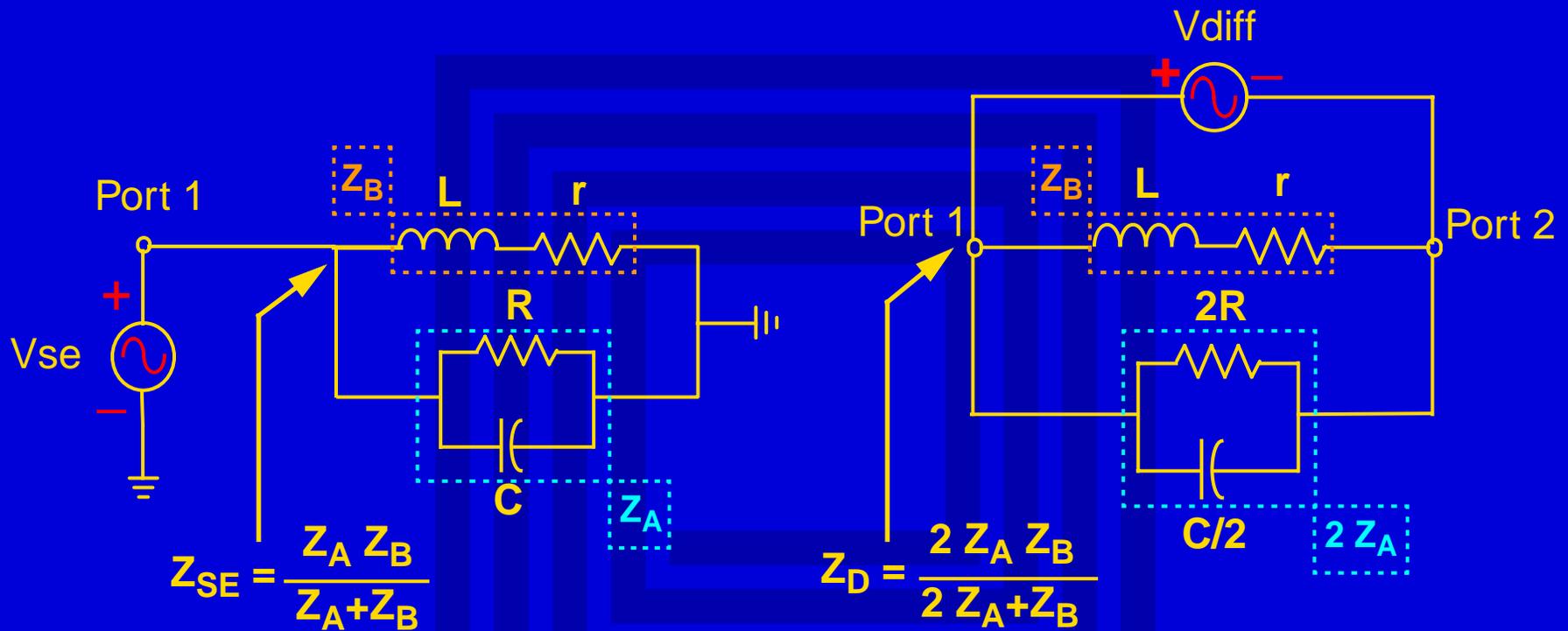
Etched cavity



Thin Membrane



# Single-ended / Differential Excitation



Single-ended model

Differential model



# Quality Factor

Below first resonant frequency of inductor

$$Q = \frac{2\pi fL}{\text{Re}[Z_{input}]}$$

- Low frequencies (<1 GHz)

$$Z_{differential} \approx Z_{single-ended}$$

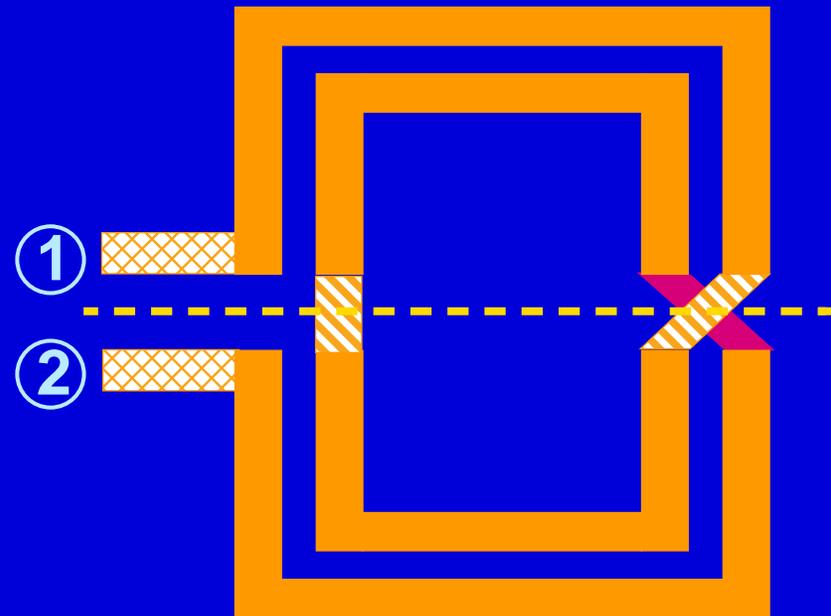
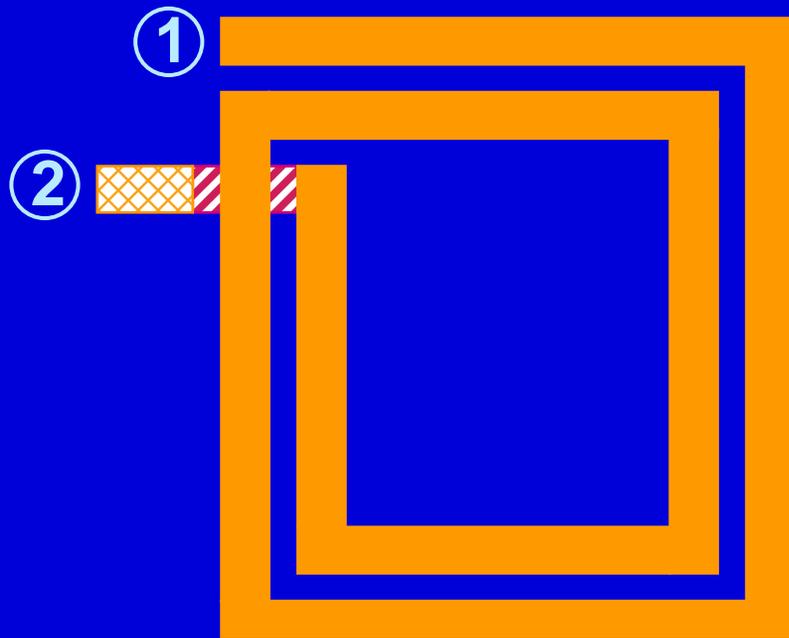
- Higher frequencies: increasing influence of substrate parasitics

$$\text{Re}[Z_{differential}] < \text{Re}[Z_{single-ended}]$$

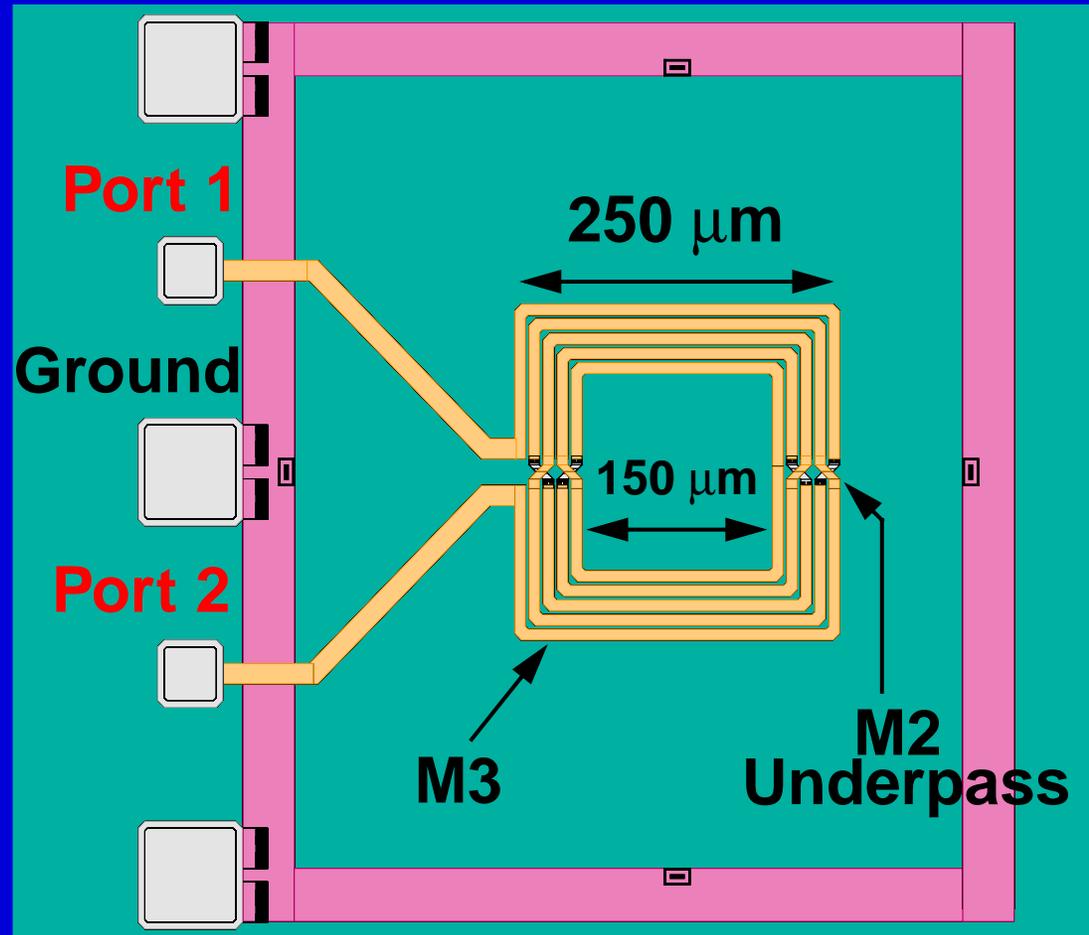
Differential excitation: Higher Q and broader bandwidth



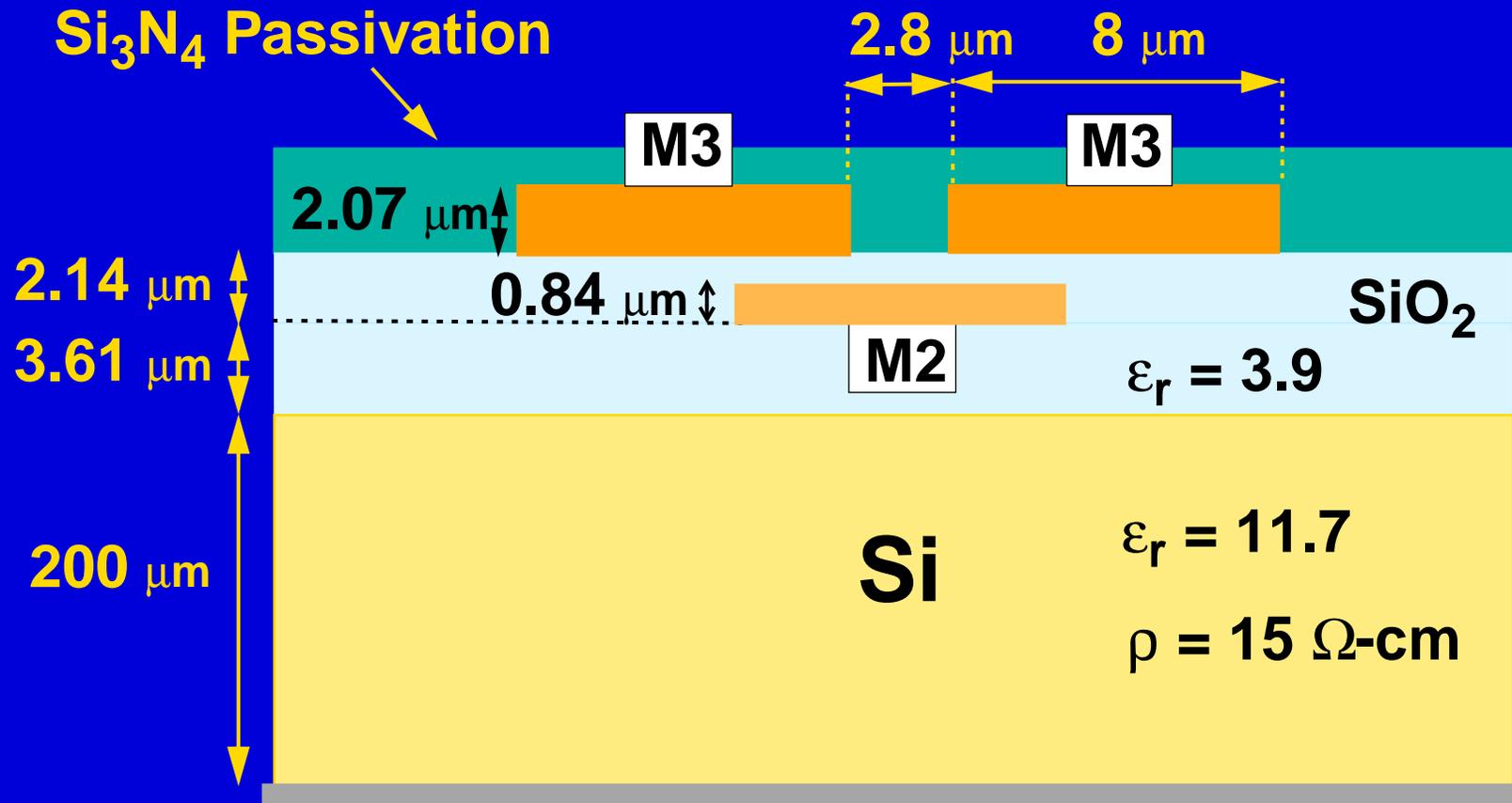
# Asymmetrical vs Symmetrical



# Symmetrical Spiral Inductor



# Technology



# Simulation / Measurement

- Full-wave EM simulation

- Measurement

2-port calibration:

- Probes on opposing sides for thru calibration
- Probes moved to same side for measurement

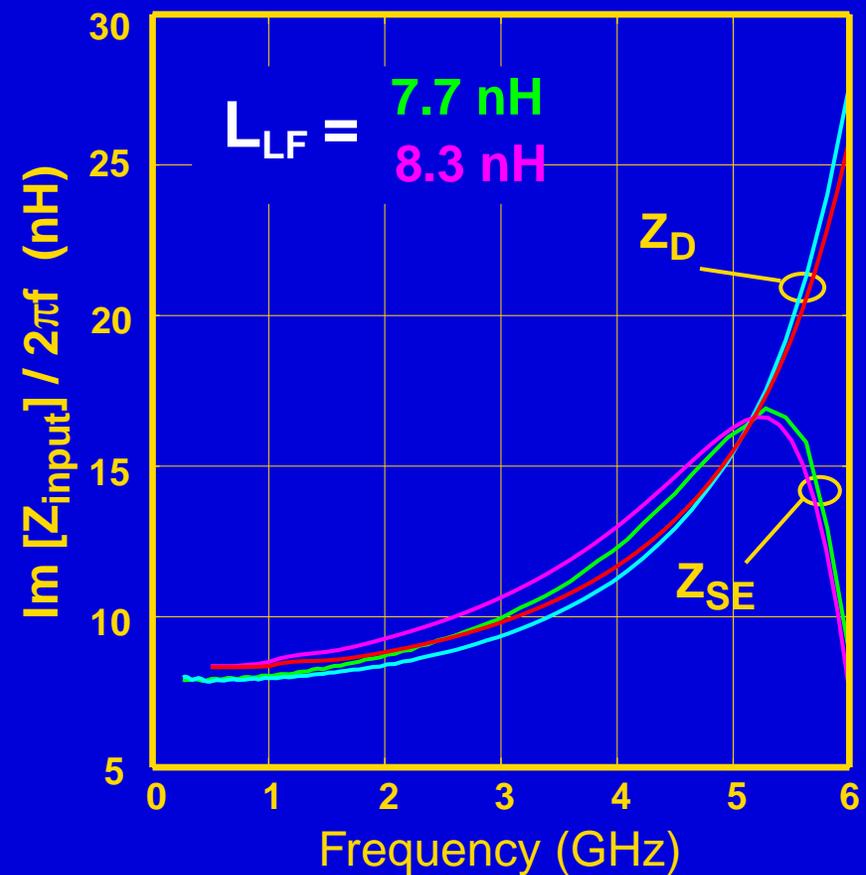
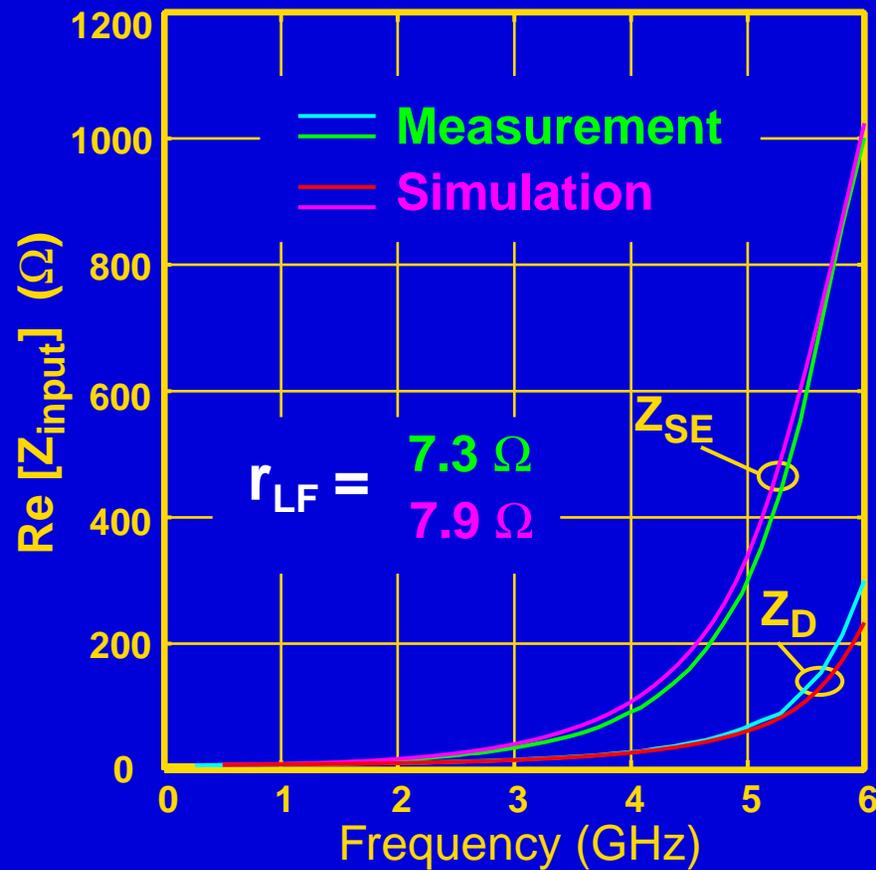
De-embedding: Open / Short

- Differential:  $S_D = S_{11} - S_{21}$

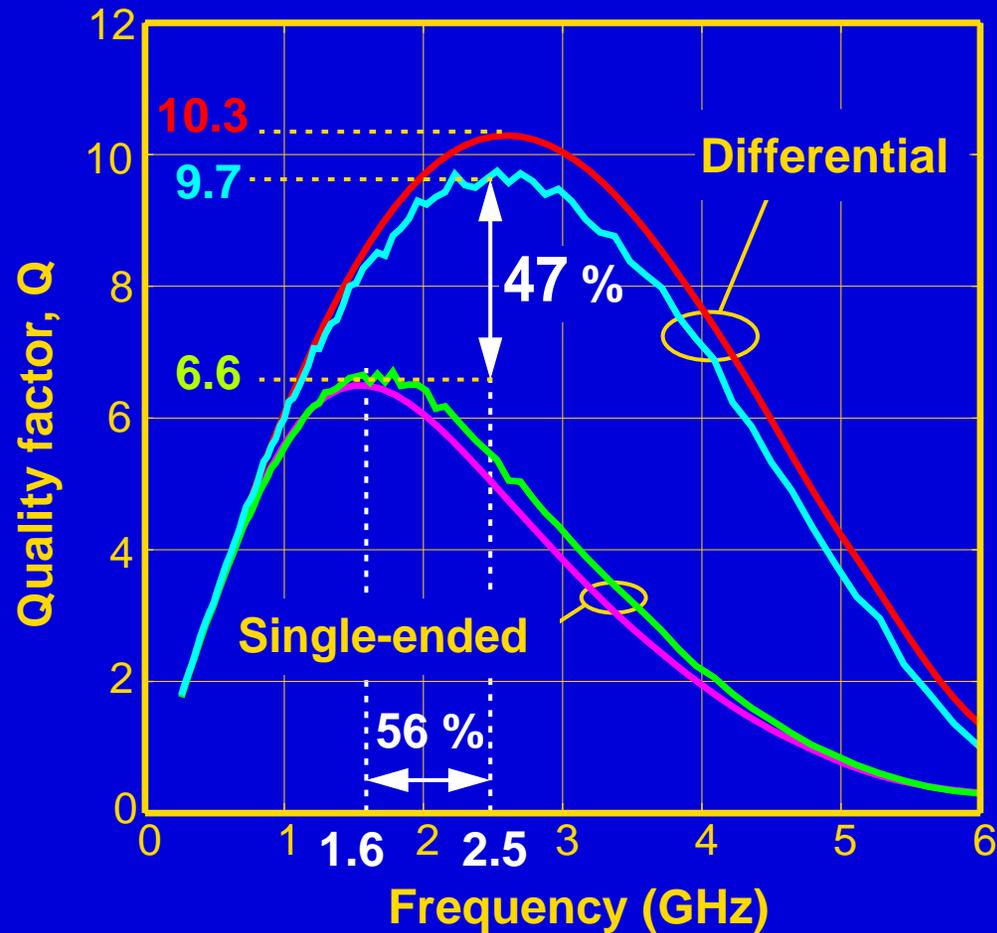
Input impedance:  $Z_D = Z_0 \left( \frac{1 + S_D}{1 - S_D} \right)$  ( $Z_0 = 100 \Omega$ )



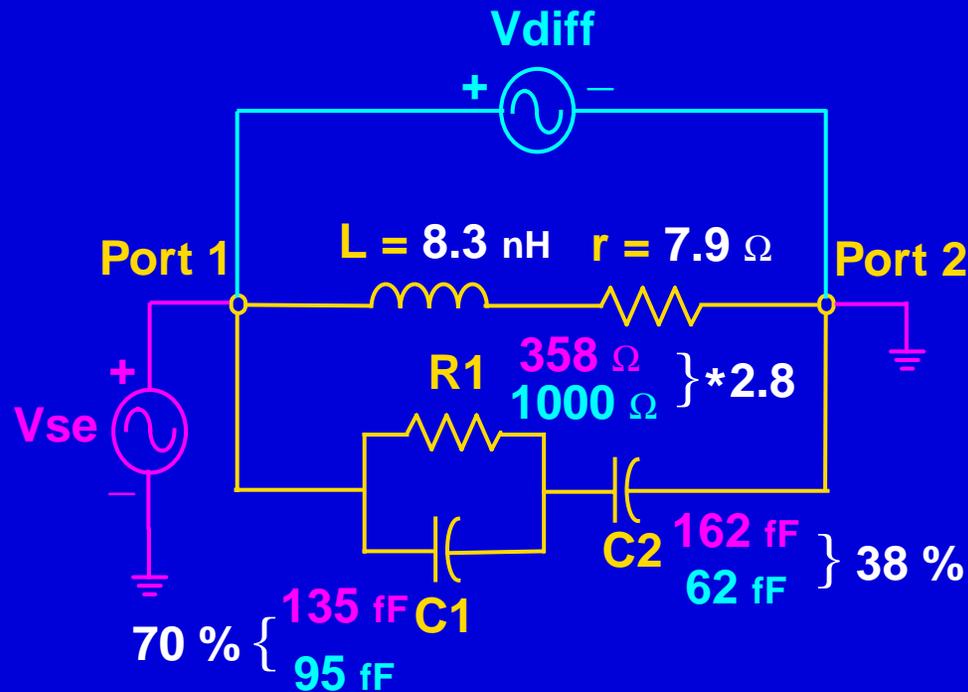
# Input Impedance



# Quality factor



# Equivalent Circuit Model



**Broadband parameter fit  
(0.5 - 6 GHz)**



# Measurement Errors

- **Topmetal thickness**

$t_{M3} + 10\% = 2.27 \mu\text{m} \longrightarrow r = 7.5 \Omega$  (Meas:  $7.3 \Omega$ )

- **NA accuracy:** connectors, cables, temperature, frequency drifts

- **Calibration**

- **De-embedding error**

Probe resistance ( $r = 0.3 \Omega$ )

Parasitics of open / short interconnects and pads

$C = 63 \text{ fF @ } 2 \text{ GHz} / L = 250 \text{ pH}, r = 0.24 \Omega$

- **Parameter variation**

Si resistivity

Layer thickness, width, spacing

Temperature

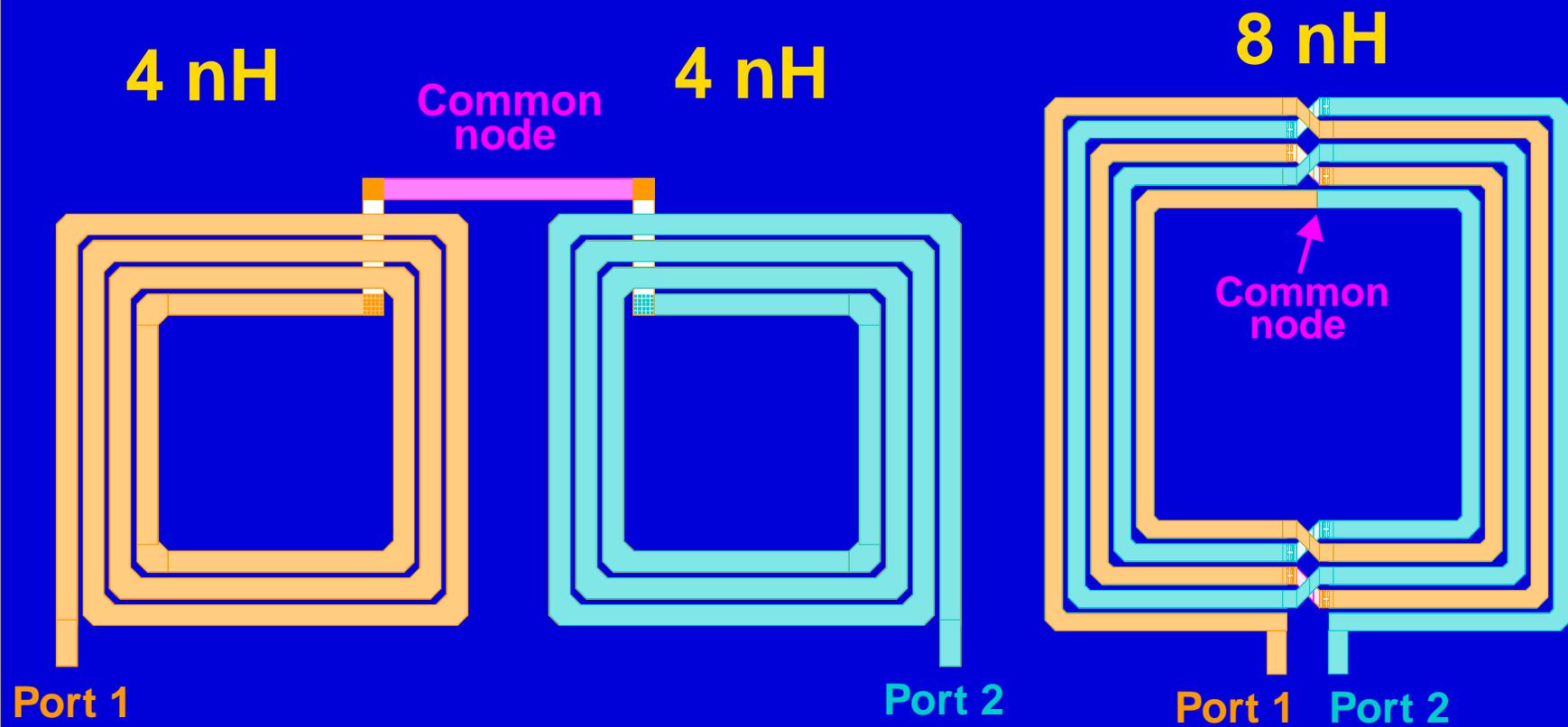


# Results

Inductor type	Reference	Si $\rho$	t ( $\mu\text{m}$ )	L (nH)	Q-factor
1-level metal	Long	10 $\Omega\text{-cm}$	1-3	1.88	6-10 @ 4 GHz
2-level metal	Park	2 k $\Omega\text{-cm}$	2	13	12 @ 3 GHz
5-level metal	Burghartz	12 $\Omega\text{-cm}$	4.3	2.2	16 @ 2 GHz
Ground shield	Yue	10-20 $\Omega\text{-cm}$	2	8	7.2 @ 1.5 GHz
Membrane	Chi	2 k $\Omega\text{-cm}$	1 (Au)	0.9 1.2	20 @ 4.3 GHz Res. freq: 70 GHz
Etched oxide/Si	Rieh	10 k $\Omega\text{-cm}$		2	Res. freq: 30 GHz
Differential Symmetrical	Danesh Long	15 $\Omega\text{-cm}$	2	8	9.7 @ 2.5 GHz



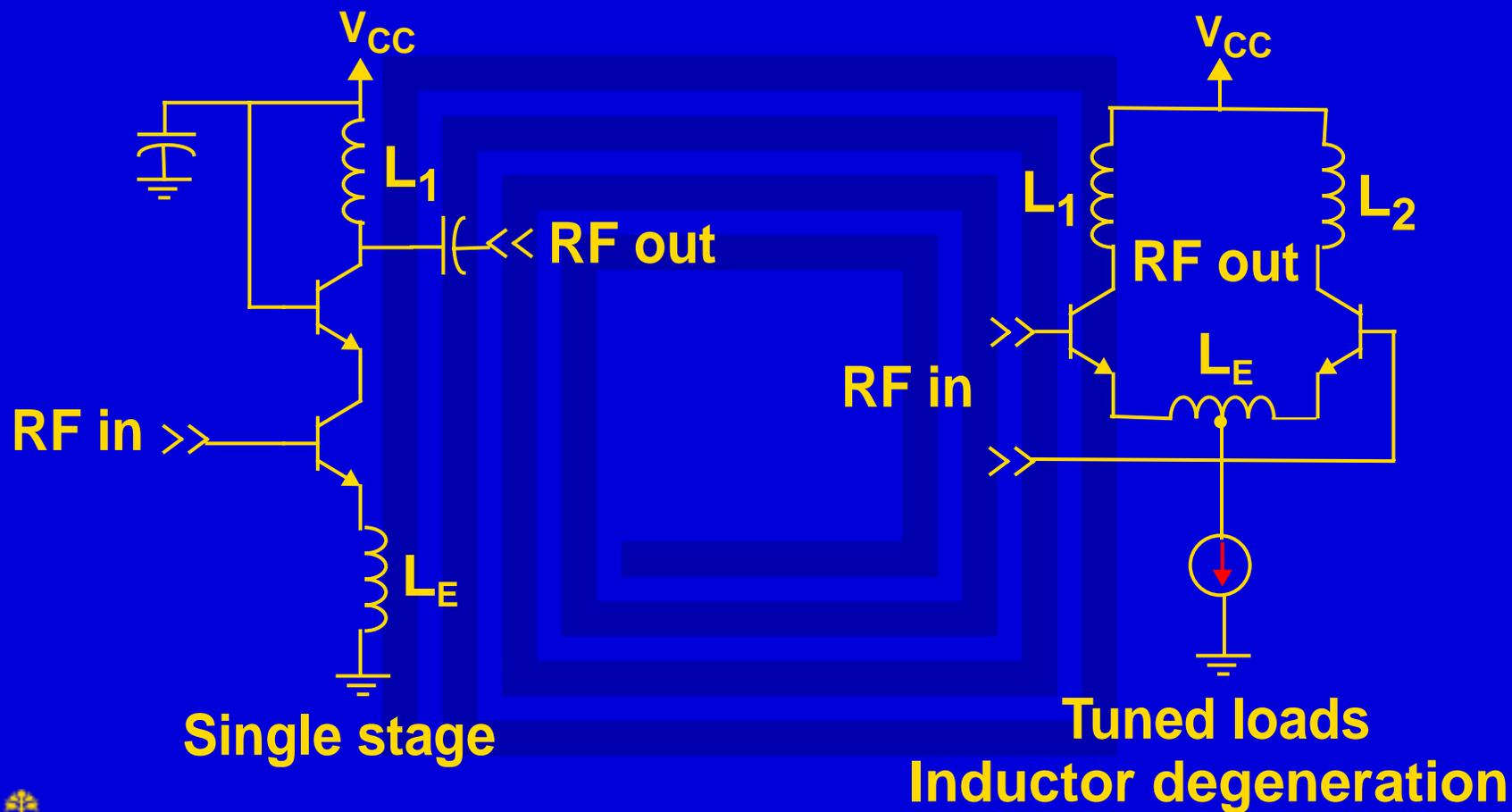
# Layout comparison



**Chip area reduction**



# Amplifier



# Conclusion

- **Differential vs single-ended excitation: lower parasitics**
  - Higher peak Q-factor (50% +)
  - Higher peak frequency (50% +)
  - Broader operating bandwidth
- **RF applications**
  - Symmetrical inductors (reduced chip area)
  - Oscillators, amplifiers, mixers ...
  - Other substrates: GaAs
- **Monolithic circuits: extra components have small marginal cost**

